

DATA SHEET

TDA2611A

5 W audio power amplifier

Product specification

November 1982



5 W audio power amplifier**TDA2611A**

The TDA2611A is a monolithic integrated circuit in a 9-lead single in-line (SIL) plastic package with a high supply voltage audio amplifier. Special features are:

- **possibility for increasing the input impedance**
- single in-line (SIL) construction for easy mounting
- very suitable for application in mains-fed apparatus
- extremely low number of external components
- thermal protection
- well defined open loop gain circuitry with simple quiescent current setting and fixed integrated closed loop gain.

QUICK REFERENCE DATA

Supply voltage range	V_P		6 to 35 V
Repetitive peak output current	I_{ORM}	<	1,5 A
Output power at $d_{tot} = 10\%$			
$V_P = 18\text{ V}; R_L = 8\ \Omega$	P_o	typ.	4,5 W
$V_P = 25\text{ V}; R_L = 15\ \Omega$	P_o	typ.	5 W
Total harmonic distortion at $P_o < 2\text{ W}; R_L = 8\ \Omega$	d_{tot}	typ.	0,3 %
Input impedance	$ Z_i $	typ.	45 k Ω
Total quiescent current at $V_P = 18\text{ V}$	I_{tot}	typ.	25 mA
Sensitivity for $P_o = 2,5\text{ W}; R_L = 8\ \Omega$	V_i	typ.	55 mV
Operating ambient temperature	T_{amb}		-25 to + 150 °C
Storage temperature	T_{stg}		-55 to + 150 °C

PACKAGE OUTLINE

9-lead SIL; plastic (SOT110B); SOT110-1.

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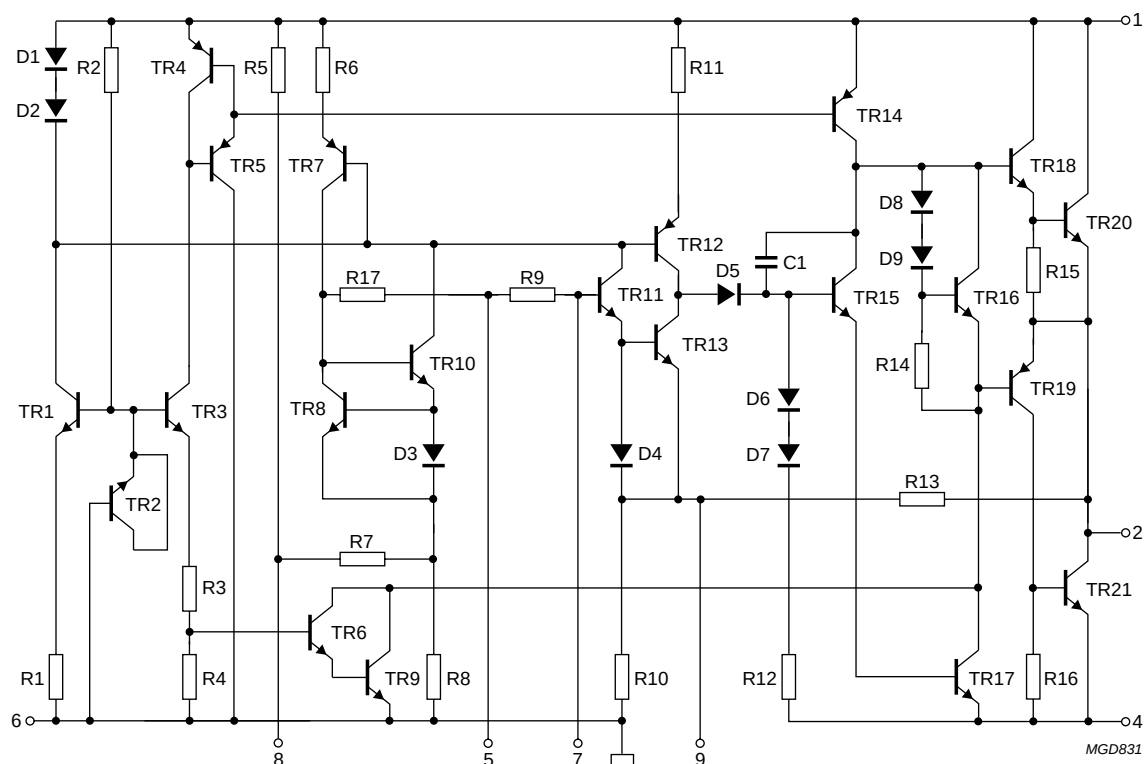


Fig.1 Circuit diagram; pin 3 not connected.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Supply voltage

 V_P max. 35 V

Non-repetitive peak output current

 I_{OSM} max. 3 A

Repetitive peak output current

 I_{ORM} max. 1,5 A

Total power dissipation

see derating curves Fig. 2

Storage temperature

 T_{stg} -55 to +150 °C

Operating ambient temperature

 T_{amb} -25 to +150 °C

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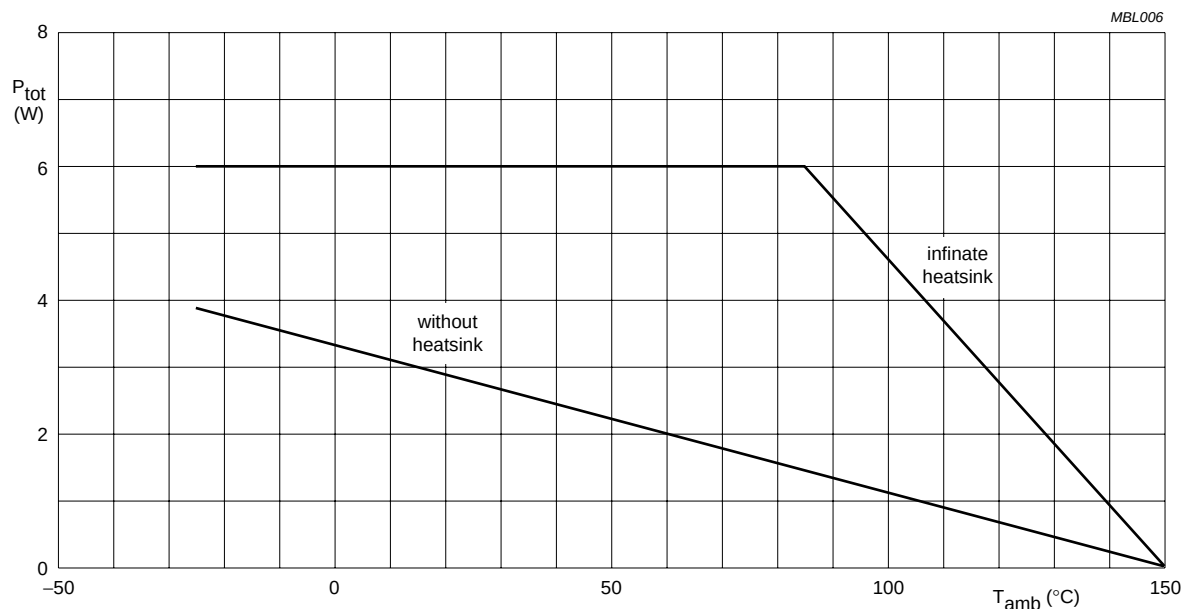


Fig.2 Power derating curves.

HEATSINK EXAMPLE

Assume $V_P = 18\text{ V}$; $R_L = 8\ \Omega$; $T_{\text{amb}} = 60\text{ }^\circ\text{C}$ maximum; $T_j = 150\text{ }^\circ\text{C}$ (max. for a 4 W application into an $8\ \Omega$ load, the maximum dissipation is about 2,2 W).

The thermal resistance from junction to ambient can be expressed as:

$$R_{\text{th } j-a} = R_{\text{th } j-tab} + R_{\text{th } tab-h} + R_{\text{th } h-a} = \frac{150 - 60}{2, 2} = 41\text{ K/W.}$$

Since $R_{\text{th } j-tab} = 11\text{ K/W}$ and $R_{\text{th } tab-h} = 1\text{ K/W}$, $R_{\text{th } h-a} = 41 - (11 + 1) = 29\text{ K/W.}$

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D.C. CHARACTERISTICS

Supply voltage range	V_P	6 to 35 V
Repetitive peak output current	I_{ORM}	< 1,5 A
Total quiescent current at $V_P = 18$ V	I_{tot}	typ. 25 mA

A.C. CHARACTERISTICS

$T_{amb} = 25$ °C; $V_P = 18$ V; $R_L = 8$ Ω ; $f = 1$ kHz unless otherwise specified; see also Fig. 3

A.F. output power at $d_{tot} = 10\%$

$V_P = 18$ V; $R_L = 8$ Ω	P_o	>	4 W
		typ.	4,5 W
$V_P = 12$ V; $R_L = 8$ Ω	P_o	typ.	1,7 W
$V_P = 8,3$ V; $R_L = 8$ Ω	P_o	typ.	0,65 W
$V_P = 20$ V; $R_L = 8$ Ω	P_o	typ.	6 W
$V_P = 25$ V; $R_L = 15$ Ω	P_o	typ.	5 W
		typ.	0,3 %
Total harmonic distortion at $P_o = 2$ W	d_{tot}	<	1 %
Frequency response		>	15 kHz
Input impedance	$ Z_i $	typ.	45 k Ω ⁽¹⁾
Noise output voltage at $R_S = 5$ k Ω ; $B = 60$ Hz to 15 kHz	V_n	typ.	0,2 mV
		<	0,5 mV
Sensitivity for $P_o = 2,5$ W	V_i	typ.	55 mV
			44 to 66 mV

Note

1. Input impedance can be increased by applying C and R between pins 5 and 9 (see also Figures 6 and 7).

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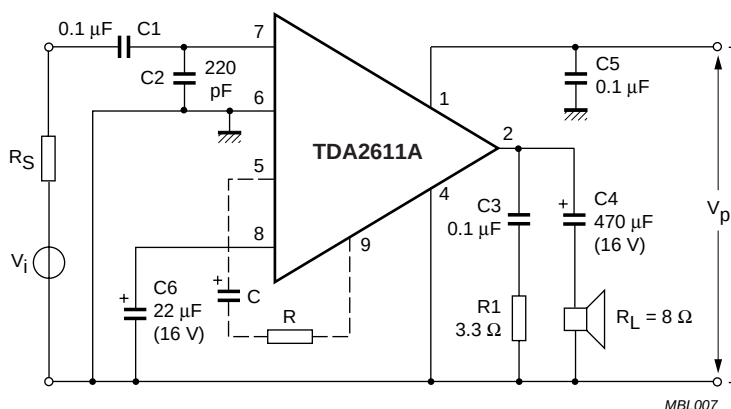
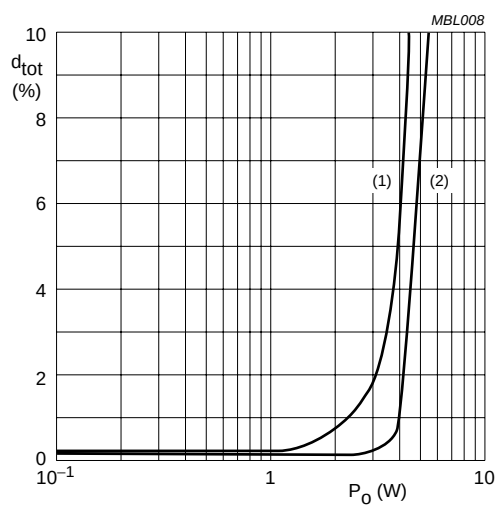


Fig.3 Test circuit; pin 3 not connected.



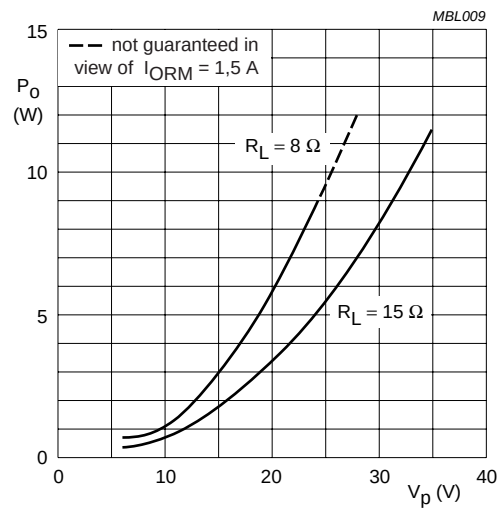
Typical values

- (1) $R_L = 8 \, \Omega$; $V_P = 18 \, \text{V}$.
- (2) $R_L = 15 \, \Omega$; $V_P = 25 \, \text{V}$.

Fig.4 Total harmonic distortion as a function of output power.

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Typical values:
 $f = 1\text{ kHz}$.
 $d_{tot} = 10\%$.

Fig.5 Output power as a function of supply voltage.

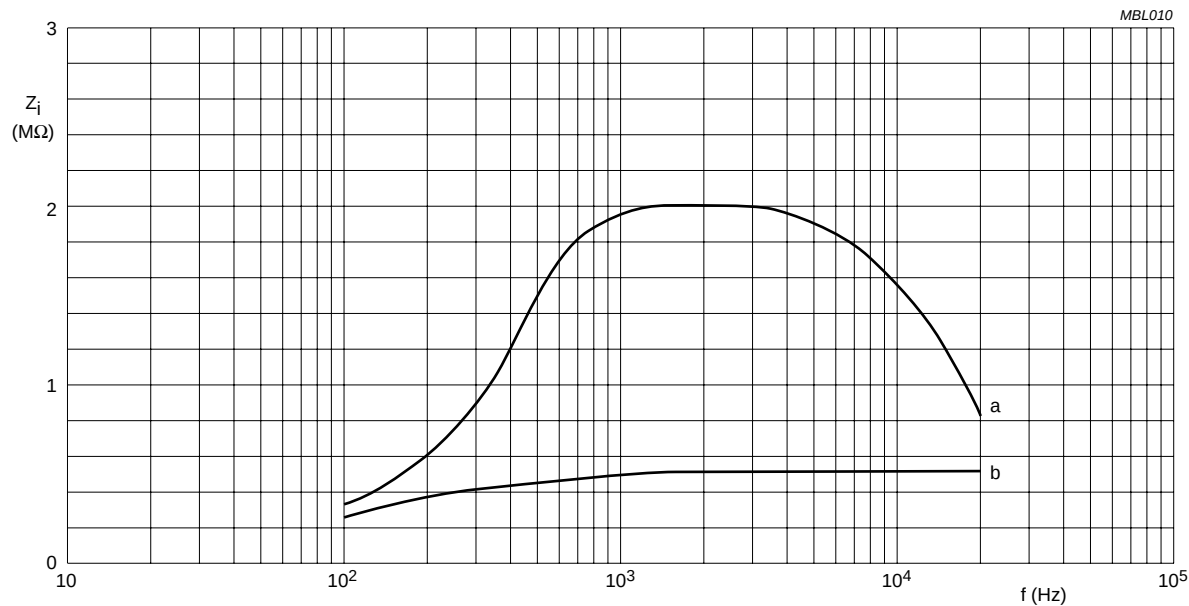


Fig.6 Input impedance as a function of frequency; curve a for $C = 1\ \mu\text{F}$, $R = 0\ \Omega$; curve b for $C = 1\ \mu\text{F}$, $R = 1\ \text{k}\Omega$; circuit of Fig. 3; $C_2 = 10\ \text{pF}$; typical values.

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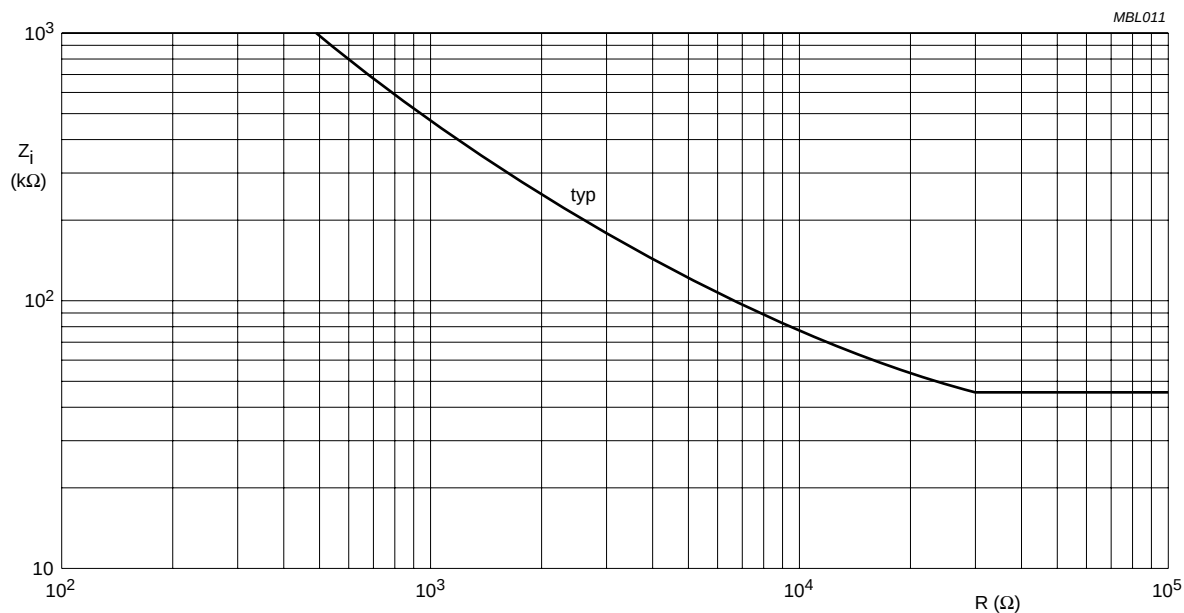


Fig.7 Input impedance as a function of R in circuit of Fig. 3; C = 1 μF; f = 1 kHz.

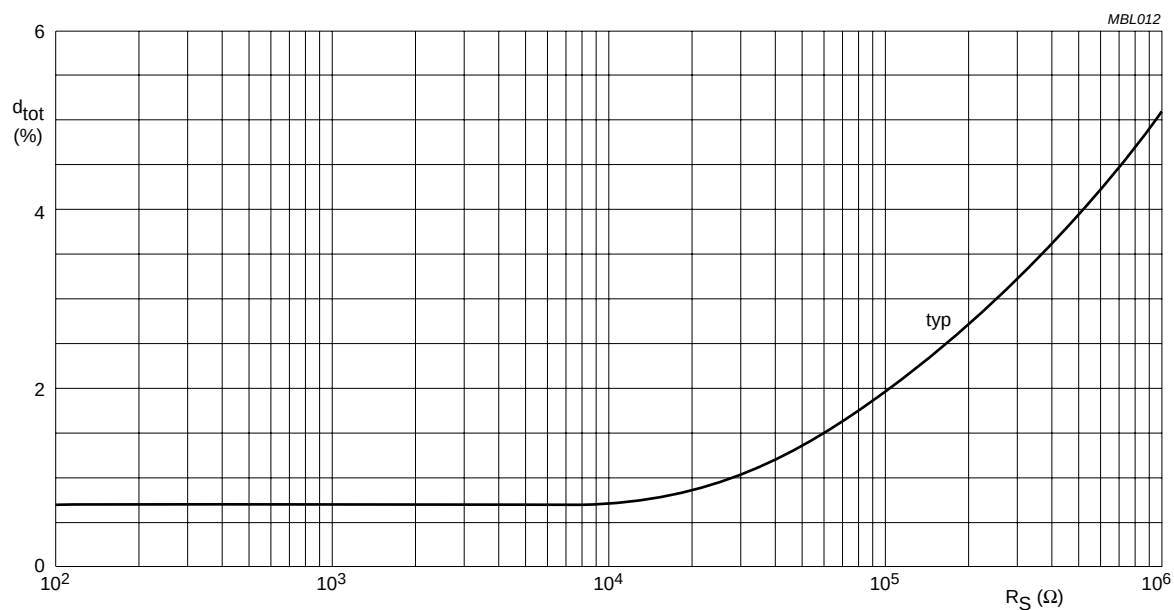


Fig.8 Total harmonic distortion as a function of R_S in the circuit of Fig. 3; P_o = 3,5 W; f = 1 kHz.

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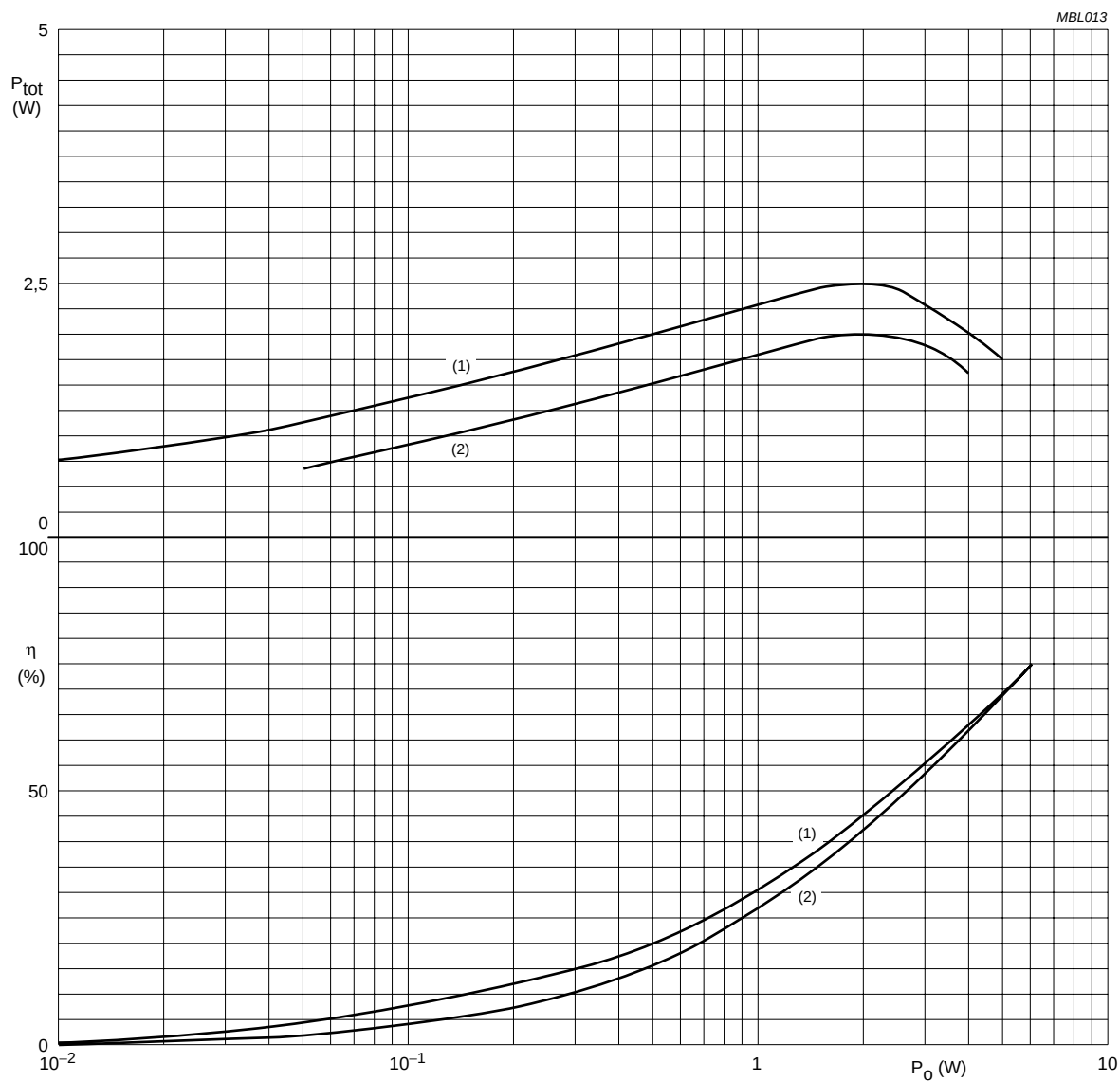


Fig.9 Total power dissipation and efficiency as a function of output power.

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APPLICATION INFORMATION

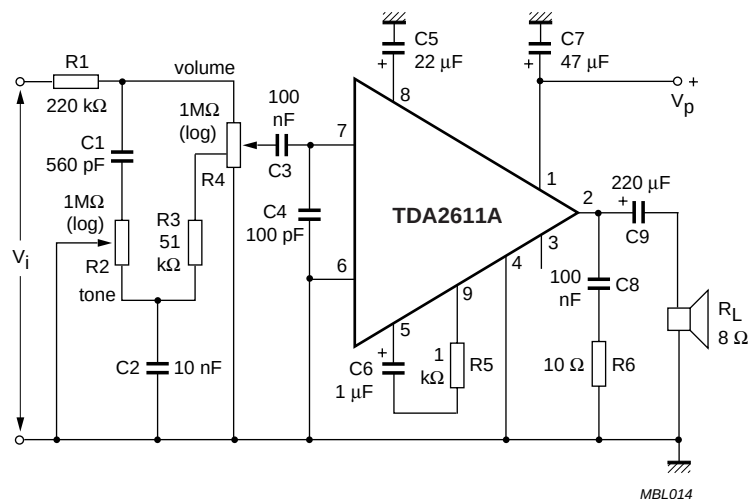
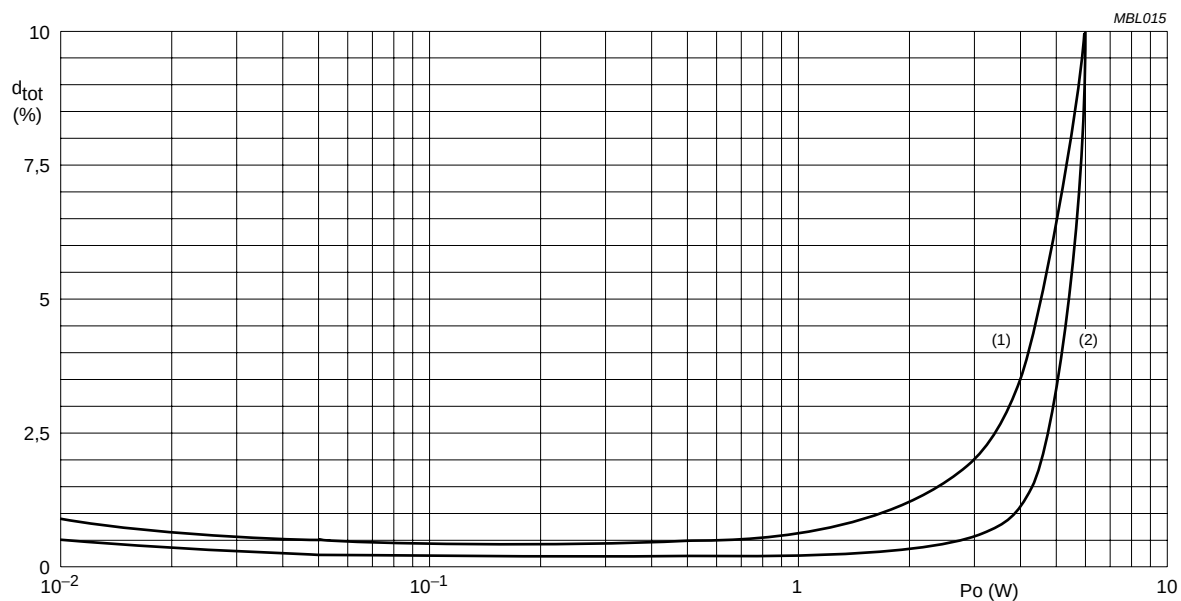


Fig.10 Ceramic pickup amplifier circuit.



- (1) With tone control.
 (2) Without tone control.

Fig.11 Total harmonic distortion as a function of output power; in circuit of Fig. 10; typical values.

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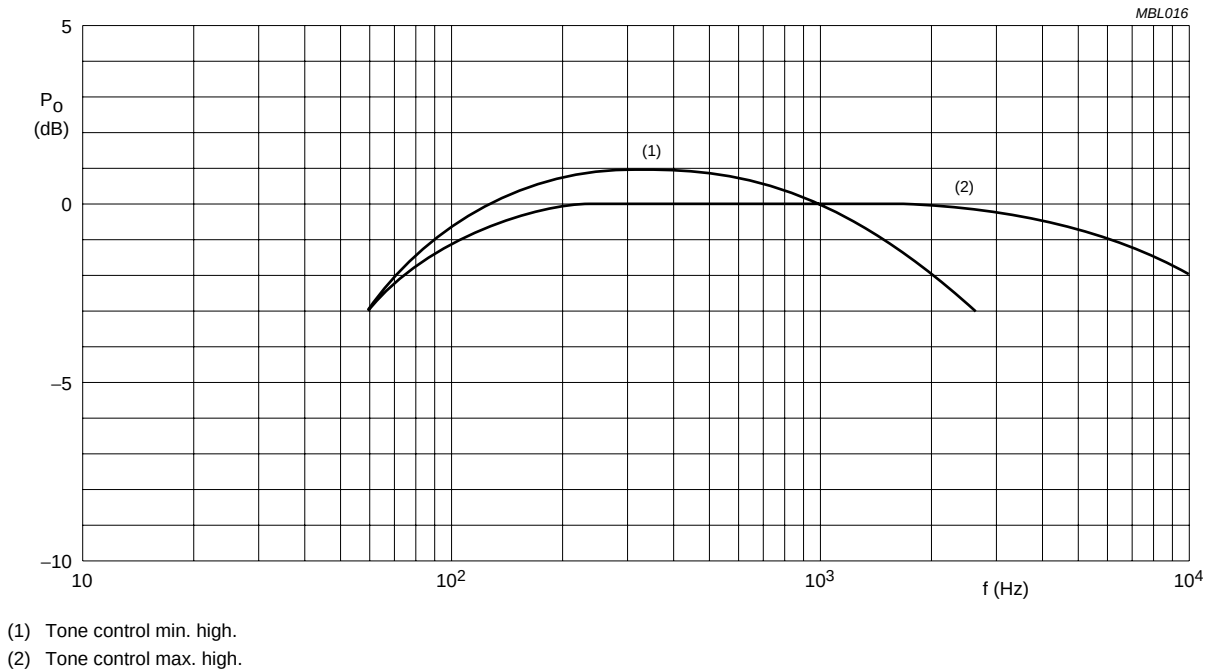


Fig.12 Frequency characteristics of the circuit of Fig. 10; P_O relative to 0 dB = 3 W; typical values.

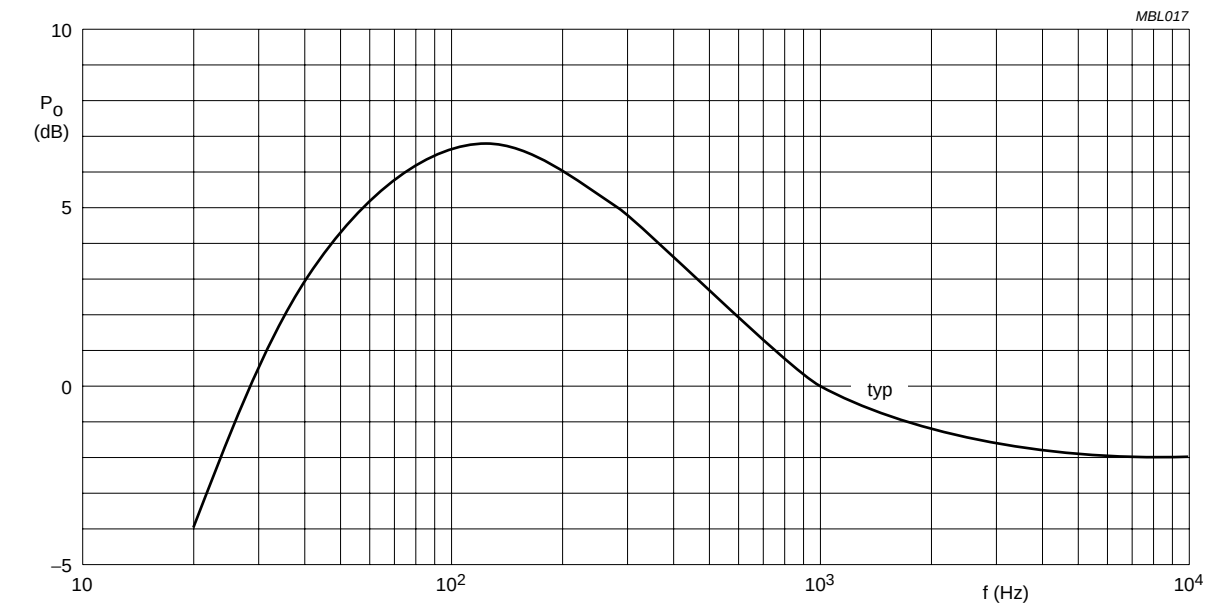


Fig.13 Frequency characteristic of the circuit of Fig. 10; volume control at the top; tone control max. high.

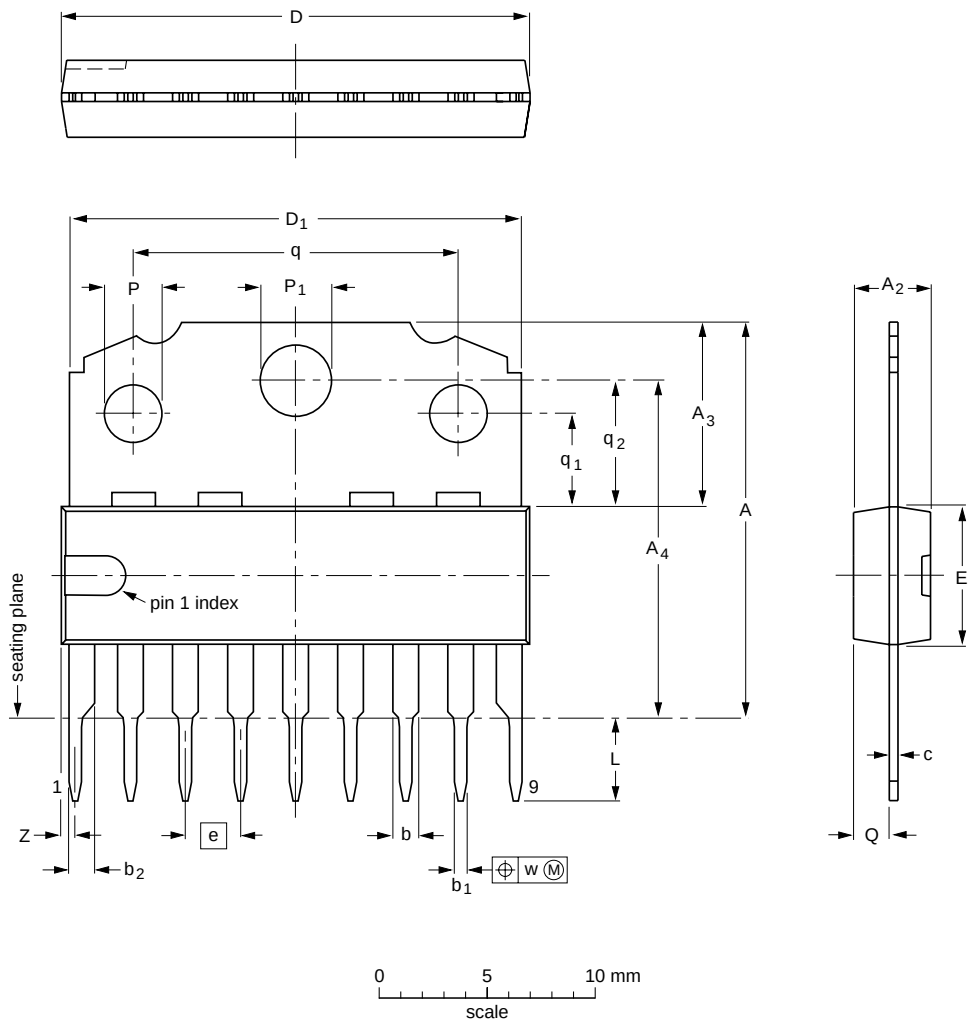
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PACKAGE OUTLINE

SIL9MPF: plastic single in-line medium power package with fin; 9 leads

SOT110-1



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₂ max.	A ₃	A ₄	b	b ₁	b ₂	c	D ⁽¹⁾	D ₁	E ⁽¹⁾	e	L	P	P ₁	Q	q	q ₁	q ₂	w	z ⁽¹⁾ max.
mm	18.5 17.8	3.7	8.7 8.0	15.8 15.4	1.40 1.14	0.67 0.50	1.40 1.14	0.48 0.38	21.8 21.4	21.4 20.7	6.48 6.20	2.54	3.9 3.4	2.75 2.50	3.4 3.2	1.75 1.55	15.1 14.9	4.4 4.2	5.9 5.7	0.25	1

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT110-1						95-02-25 03-03-12

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SOLDERING**Introduction**

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact

with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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